# CAN Bus Protector, Dual Line

# NUP3125, SZNUP3125

The SZ/NUP3125 has been designed to protect the CAN transceiver in 24 V designs from ESD and other harmful surge protection events. This device provides bidirectional protection for each data line with a single compact SC-70 (SOT-323) package, giving the system designer a low cost option for improving system reliability and meeting stringent EMI requirements.

#### **Features**

- 120 W Peak Power Dissipation per Line (8/20 μs Waveform)
- Diode Capacitance Matching
- Low Reverse Leakage Current (< 100 nA)
- IEC Compatibility: IEC 61000-4-2 (ESD): Level 4
  - IEC 61000-4-4 (EFT): 50 A 5/50 ns
  - IEC 61000-4-5 (Lighting) 2.0 A (8/20 μs)
- Flammability Rating UL 94 V-0
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

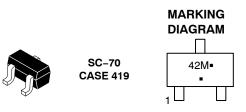
#### **Applications**

- Automotive Networks
  - CAN / CAN-FD
  - Low and High-Speed CAN
  - Fault Tolerant CAN
  - Trucks
- Industrial Control Networks
  - Smart Distribution Systems (SDS)
  - DeviceNet



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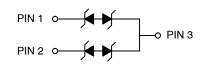
www.onsemi.com

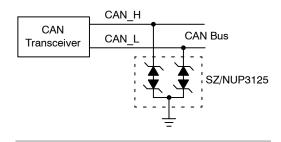


42 = Specific Device Code

M = Date Code

= Pb-Free Package
 (Note: Microdot may be in either location)





## **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

# NUP3125, SZNUP3125

## MAXIMUM RATINGS (T<sub>J</sub> = 25°C, unless otherwise specified)

Symbol	Rating	Value	Unit
P <sub>PK</sub>	Peak Power Dissipation, 8/20 μs Double Exponential Waveform (Note 1)	120	W
TJ	T <sub>J</sub> Operating Junction Temperature Range T <sub>J</sub> Storage Temperature Range		°C
TJ			°C
TL	Lead Solder Temperature (10 s)	260	°C
ESD	Human Body Model (HBM) Machine Model (MM) IEC 61000-4-2 (Contact) IEC 61000-4-2 (Air)	8.0 1.6 21 21	kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C, unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V <sub>RWM</sub>	Reverse Working Voltage	(Note 2)	-	-	32	V
V <sub>BR</sub>	Breakdown Voltage I <sub>T</sub> = 1 mA (Note 3)		35.6	39	-	V
I <sub>R</sub>	Reverse Leakage Current	verse Leakage Current V <sub>RWM</sub> = 32 V -		-	100	nA
V <sub>C</sub>	Clamping Voltage	8/20 μs Waveform (Note 4) I <sub>PP</sub> = 1 A I <sub>PP</sub> = 2 A	- -	47 57	55 60	V
I <sub>PP</sub>	Maximum Peak Pulse Current	8/20 μs Waveform (Note 4)	-	-	2.0	Α
CJ	Capacitance	V <sub>R</sub> = 0 V, f = 1 MHz (Line to GND)	-	5.7	10	pF
		V <sub>R</sub> = 5 V, f = 1 MHz (Line to GND)	-	4.5	6.0	pF
		$V_R = 5 \text{ V, f} = 1 \text{ MHz (Line to GND)},$ $T_J = 150^{\circ}\text{C}$	-	5.0		pF
ΔC	Diode Capacitance Matching	V <sub>R</sub> = 0 V, 5 MHz (Note 5)	-	0.26	2	%

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NUP3125WTT1G	SC-70 (Pb-Free)	3000 / Tape & Reel
SZNUP3125WTT1G	SC-70 (Pb-Free)	3000 / Tape & Reel
NUP3125WTT3G	SC-70 (Pb-Free)	10000 / Tape & Reel
SZNUP3125WTT3G	SC-70 (Pb-Free)	10000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>1.</sup> Non-repetitive current pulse per Figure 1.

<sup>2.</sup> Surge protection devices are normally selected according to the working peak reverse voltage (V<sub>RWM</sub>), which should be equal or greater than the DC or continuous peak operating voltage level.

<sup>3.</sup> V<sub>BR</sub> is measured at pulse test current I<sub>T</sub>.

<sup>4.</sup> Pulse waveform per Figure 1.

ΔC is the percentage difference between C<sub>J</sub> of lines 1 and 2 measured according to the test conditions given in the electrical characteristics table.

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# **TYPICAL PERFORMANCE CURVES**

 $(T_J = 25^{\circ}C \text{ unless otherwise noted})$ 

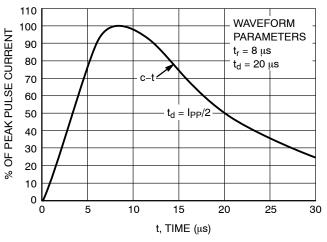
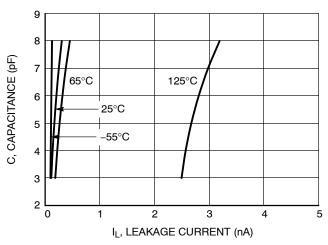


Figure 1. Pulse Waveform, 8/20 μs

Figure 2. IV Characteristics



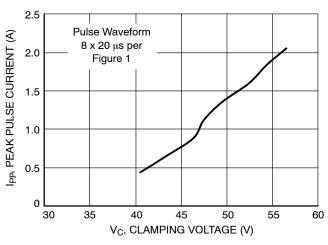


Figure 3. IR vs Temperature Characteristics

Figure 4. Clamping Voltage vs. Peak Pulse Current

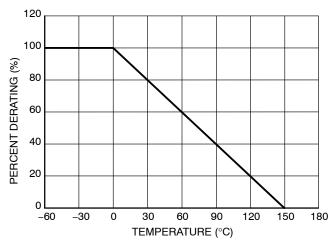


Figure 5. Temperature Power Dissipation Derating

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#### **Surge Protection Diode Circuit**

Surge protection diodes provide protection to a transceiver by clamping a surge voltage to a safe level. Surge protection diodes have high impedance below and low impedance above their breakdown voltage. A surge protection Zener diode has its junction optimized to absorb the high peak energy of a transient event, while a standard Zener diode is designed and specified to clamp a steady state voltage.

Figure 6 provides an example of a dual bidirectional surge protection diode array that can be used for protection with the high-speed CAN network. The bidirectional array is created from four identical Zener TVS diodes. The clamping voltage of the composite device is equal to the

breakdown voltage of the diode that is reversed biased, plus the diode drop of the second diode that is forwarded biased.

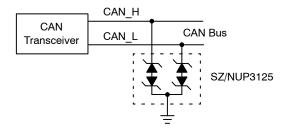


Figure 6. High-Speed and Fault Tolerant CAN Surge Protection Circuit





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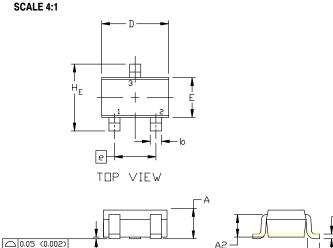
END VIEW

**DATE 11 OCT 2022** 

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH

	MILLIMETERS			INCHES		
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF		0.028 BSC			
b	0.30	0.35	0.40	0.012	0.014	0.016
С	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.00	2.20	0.071	0.080	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
е	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC		0.026 BSC			
L	0.20	0.38	0.56	0.008	0.015	0.022
HE	2.00	2.10	2.40	0.079	0.083	0.095



# GENERIC MARKING DIAGRAM

SIDE VIEW

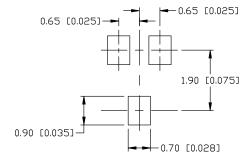


XX = Specific Device Code

M = Date Code

■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



For additional information on our Pb-Free strategy and soldering details, please download the IIN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

SOLDERING FOOTPRINT

STYLE 1: CANCELLED	STYLE 2: PIN 1. ANODE 2. N.C. 3. CATHODE	STYLE 3: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. CATHODE	
STYLE 6:	STYLE 7:	STYLE 8:	STYLE 9:	STYLE 10:	STYLE 11:
PIN 1. EMITTER	PIN 1. BASE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. CATHODE
2. BASE	2. EMITTER	2. SOURCE	2. CATHODE	2. ANODE	<ol><li>CATHODE</li></ol>
<ol><li>COLLECTOR</li></ol>	<ol><li>COLLECTOR</li></ol>	3. DRAIN	<ol><li>CATHODE-ANODE</li></ol>	3. ANODE-CATHODE	<ol><li>CATHODE</li></ol>

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